



Flash Memory Summit



3D Flash Leads to More Powerful Embedded Applications

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Outline

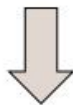


- Embedded SSD Unique in Every Way
- The Benefits as migrating to 3D Technology
- The Challenges on 3D NAND



Embedded SSD - Unique in Every Way

Features	Usage Behavior	Validation
<ul style="list-style-type: none">•Vaulting•pFail•SATA Link Loss•Logging•Encryption	<ul style="list-style-type: none">•Read Intensive•4K Random•Mix WL•Read Only Mode	<ul style="list-style-type: none">•Compatibility•Pattern scheme•Environment



AUTOMOTIVE



**FACTORY
AUTOMATION**



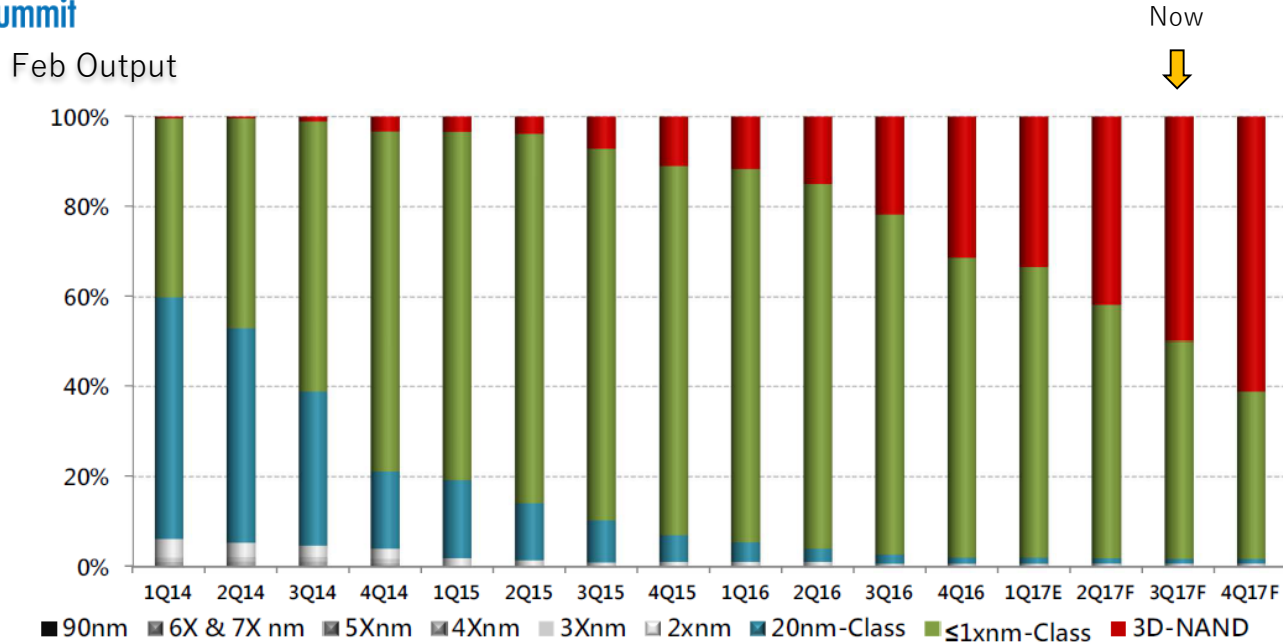
**TRANSPORTATION
VIDEO
SURVEILLANCE**



**KIOSK/GAMING/
DIGITAL SIGNAGE**



NAND Technology Trend



- 2D NAND: No more migration after 1Znm process
- 3D NAND: >50% after Q4 17'



3D Advantage Over 2D NAND

	2D MLC	3D TLC	
Cost per bit	High \$\$	Low \$	✓
Die Density	64Gb and Up	128Gb and Up	✓
Max Data Rate	333- 400MT/s	400- 533MT/s	✓
Power	=	Up to 22% Power Efficiency	✓
Endurance	=	= (with LDPC)	✓
Package	=	Footprint match with 2D MLC	✓

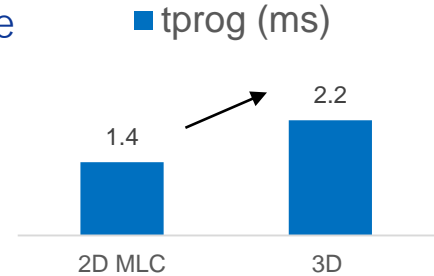
3D Implement Challenges

- Challenge 1: **Throughput** impact on small capacity
- Challenge 2: **Latency** impact due to page # increase



Potential Impact 1: Throughput

- Problem: 1. Mono density double leads to less chip enable
2. 3D flash program time increases



- Solution: Full program sequence (FPS) technology
MB/s per CE speed improvement: 25MB/s → 45MB/s

	2D MLC	3D TLC (w/o FPS)	3D TLC (with FPS)
Performance (32GB)	520/100 (64Gb x 4 → 4CE)	550/50 (128Gb x 2 → 2CE)	550/90 (128Gb x 2 → 2CE)

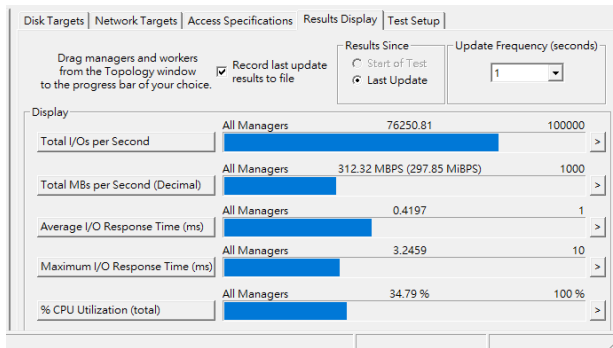


Potential Impact 2: Latency

- Problem: due to page # per block increase (256 → 768), it prolongs garbage collection time to free up one spare block which result to worse latency performance.
- Solution: Proprietary firmware GC optimization

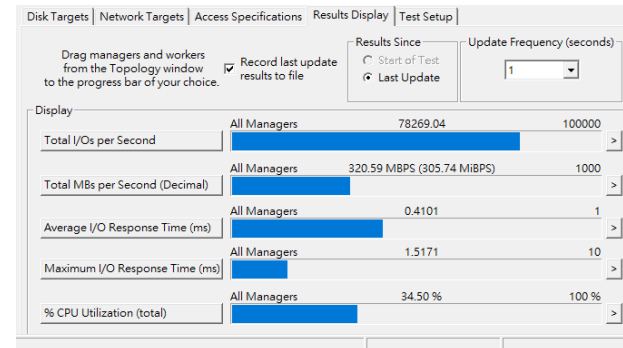
2D MLC 480GB

Avg: 0.4197ms
Max: 3.2459ms



3D TLC 480GB

Avg: 0.4101ms
Max: 1.5171ms





Take-Aways

- 3D NAND anticipates continued MLC/TLC bit cost reduction while driving density growth over next years.
- The traditional rule of thumb still intact- Keeping flexibility, responsive, adaptive.
- 3D NAND brings benefits of density, power, endurance.
- Controller vendor plays key role for conquering key challenges (throughput and latency) on 3D transition in embedded market.

For more information on Phison SSD Controllers,
please visit us at

Booth #614



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Thank You!